

EKC245™

EKC PlasmaSolv® Line - HDA™ Technology

High Purity Specifications for Advanced Wafer Cleaning

Removes Residues from Vias

Cleans HBr Etched Polysilicon

Removes Residues after Metal Etch

Operates Below Flashpoint

Low evaporation Rate at Operating Temperatures

Does Not Require Ultrasonics

Rinses in Water

Compatible with Automatic Equipment

Great Device Reliability and Product Yields

Lowers Via Contact Resistance

Maintains Gate Oxide Integrity

Improves Contact Between Metal Layers

Combines Wet Chemical Processes

Provides a Safe Chemical Process

Extends Bath Life, Reduces Air Emissions, Lowers Factory Operating Cost

Reduces Equipment requirements

Reduces Cost of Ownership by Simplifying Process

Offers Flexibility in Process

0.5µm Metal Lines



53701c

Before Clean



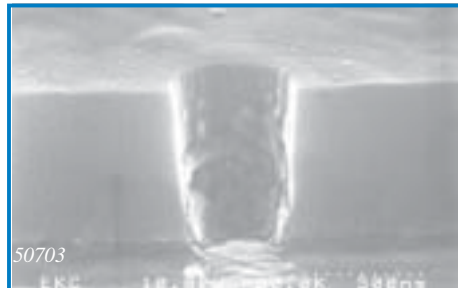
53746H2b

After Clean

EKC245™
U.S. and Foreign
Patents Pending

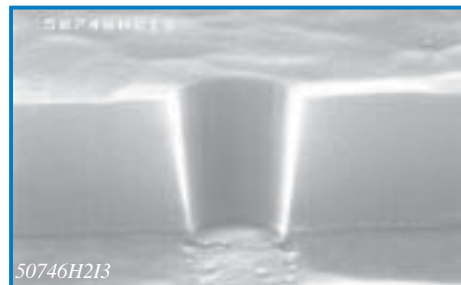
**Ox/Ti/AlCu/TiN
20 min. @ 65°C**

0.5µm Via



50703

Before Clean



50746H213

After Clean

**AlSiCu/TiN/TEOS
20 min. @ 65°C**

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DuPont Electronic Technologies

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